

MOSFET – P-Channel, POWERTRENCH®

-150 V, -0.8 A, 1.2 Ω

FDN86265P

General Description

This P-Channel MOSFET is produced using onsemi's advanced POWERTRENCH process that has been optimized for the on-state resistance and yet maintain superior switching performance.

Features

- Max $r_{DS(on)}$ = 1.2 Ω at $V_{GS} = -10$ V, $I_D = -0.8$ A
Max $r_{DS(on)}$ = 1.4 Ω at $V_{GS} = -6$ V, $I_D = -0.7$ A
- Very Low RDS-on Mid Voltage P-Channel Silicon Technology Optimised for Low Qg
- This Product is Optimised for Fast Switching Applications as Well as Load Switch Applications
- 100% UIL Tested
- Pb-Free, Halide Free and RoHS Compliant
- HBM ESD Level Class 0B, CDM ESD Level Class C3 (Note 4)

Applications

- Active Clamp Switch
- Load Switch

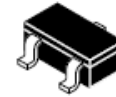
ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted.)

Symbol	Parameter	Value	Unit
V _{DS}	Drain to Source Voltage	-150	V
V _{GS}	Gate to Source Voltage	±25	V
I _D	Drain Current – Continuous (Note 1a) – Pulsed	-0.8 -5	A
E _{AS}	Single Pulse Avalanche Energy (Note 3)	6	mJ
P _D	Power Dissipation (Note 1a) (Note 1b)	1.5 0.6	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

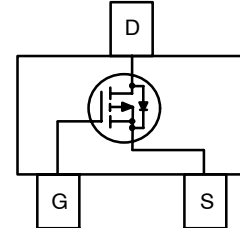
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted.)

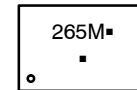
Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction to Case (Note 1)	75	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient (Note 1a)	80	°C/W



SOT-23/SUPERSOT™ -23, 3 LEAD,
1.4x2.9
CASE 527AG



MARKING DIAGRAM



- 265 = Specific Device Code
- M = Month Code
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
FDN86265P	SOT-23 (Pb-Free/ Halide Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

FDN86265P

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted.)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
--------	-----------	-----------------	-----	-----	-----	------

OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = -250 μA, V _{GS} = 0 V	-150	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = -250 μA, referenced to 25°C	-	-129	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -120 V, V _{GS} = 0 V	-	-	-1	μA
I _{GSS}	Gate-Body Leakage	V _{GS} = ±25 V, V _{DS} = 0 V	-	-	±100	nA

ON CHARACTERISTICS (Note 2)

V _{GS(th)}	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = -250 μA	-2	-3.3	-4	V
ΔV _{GS(th)} / ΔT _J	Gate to Source Threshold Voltage Temperature Coefficient	I _D = -250 μA, referenced to 25°C	-	5	-	mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = -10 V, I _D = -0.8 A V _{GS} = -6 V, I _D = -0.7 A V _{GS} = -10 V, I _D = -0.8 A, T _J = 125°C	-	0.85 0.96 1.54	1.2 1.4 2.2	Ω
g _{FS}	Forward Transconductance	V _{DS} = -10 V, I _D = -0.8 A	-	1.5	-	S

DYNAMIC CHARACTERISTICS

C _{ISS}	Input Capacitance	V _{DS} = -75 V, V _{GS} = 0 V, f = 1 MHz	-	158	210	pF
C _{OSS}	Output Capacitance		-	17	25	pF
C _{RSS}	Reverse Transfer Capacitance		-	1.6	5	pF
R _g	Gate Resistance		0.1	3.3	6.7	Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = -75 V, I _D = -0.8 A, V _{GS} = -10 V, R _{GEN} = 6 Ω	-	5.7	12	ns
t _r	Rise Time		-	2.2	10	ns
t _{d(off)}	Turn-Off Delay Time		-	7.9	16	ns
t _f	Fall Time		-	9.9	20	ns
Q _g	Total Gate Charge		V _{GS} = 0 V to -10 V, V _{DD} = -75 V, I _D = -0.8 A,	-	2.9	4.1
Q _{gs}	Gate to Source Gate Charge	V _{DD} = -75 V, I _D = -0.8 A	-	0.8	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	0.8	-	nC

DRAIN-SOURCE DIODE CHARACTERISTICS

V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = -0.8 A (Note 2)	-	-0.86	-1.3	V
t _{rr}	Reverse Recovery Time	I _F = -0.8 A, di/dt = 100 A/μs	-	49	78	ns
Q _{rr}	Reverse Recovery Charge		-	70	112	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

- R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.



a) 80°C/W when mounted on a 1 in² pad of 2 oz. copper.



b) 180°C/W when mounted on a minimum pad.

- Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%.
- Starting T_J = 25°C; N-ch: L = 3 mH, I_{AS} = -2 A, V_{DD} = -150 V, V_{GS} = -10 V. 100% test at L = 0.1 mH, I_{AS} = -9 A.
- ESD between the gate and source serves only, no gate overvoltage rating is implied.

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

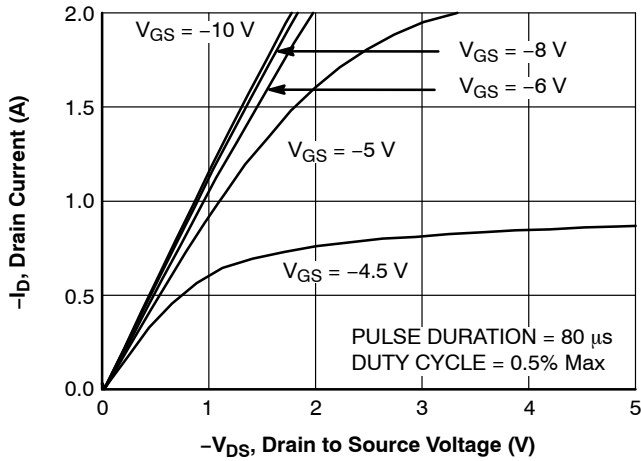


Figure 1. On Region Characteristics

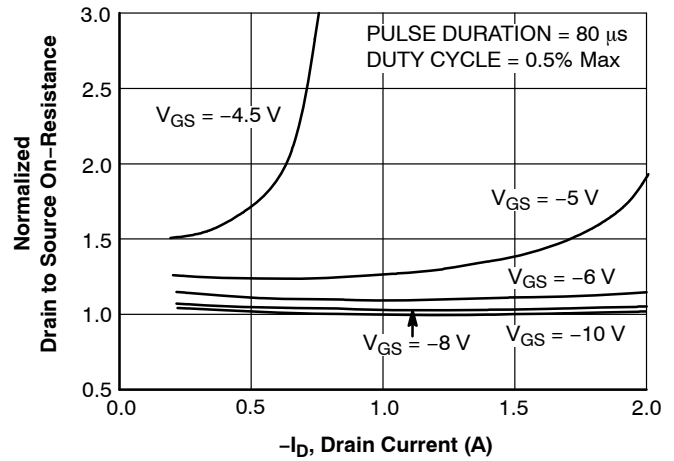


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

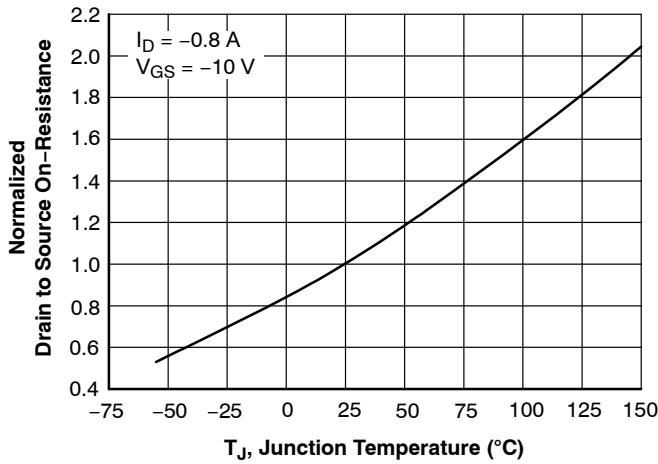


Figure 3. Normalized On Resistance vs. Junction Temperature

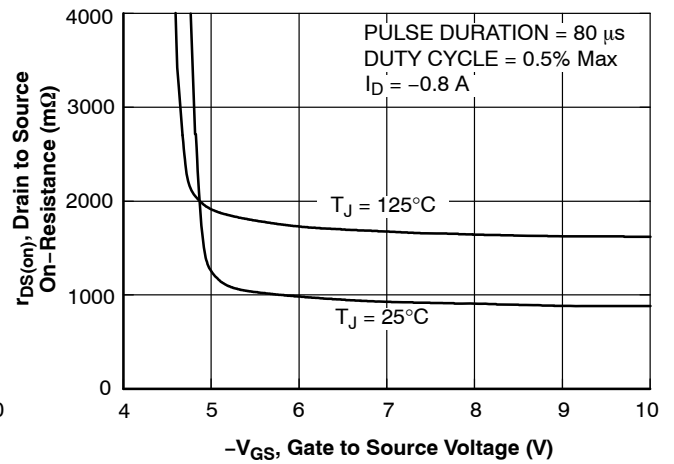


Figure 4. On-Resistance vs. Gate to Source Voltage

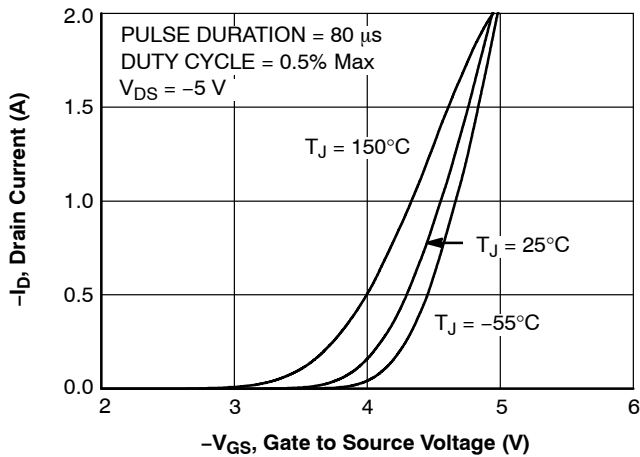


Figure 5. Transfer Characteristics

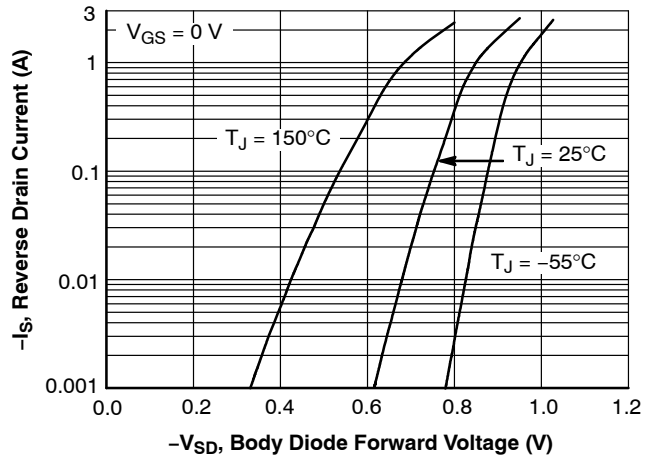


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

FDN86265P

TYPICAL CHARACTERISTICS (CONTINUED)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

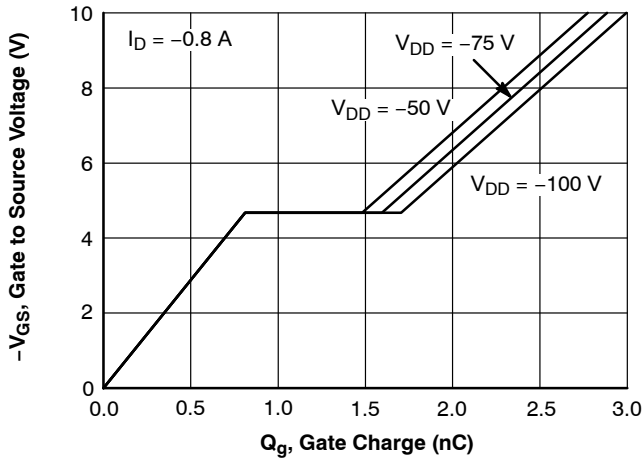


Figure 7. Gate Charge Characteristics

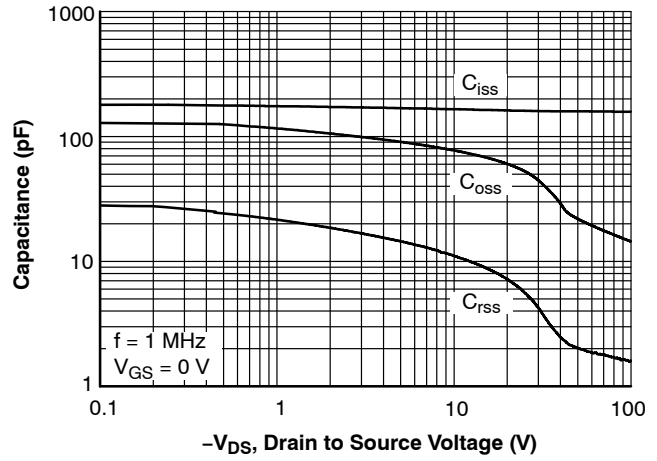


Figure 8. Capacitance vs. Drain to Source Voltage

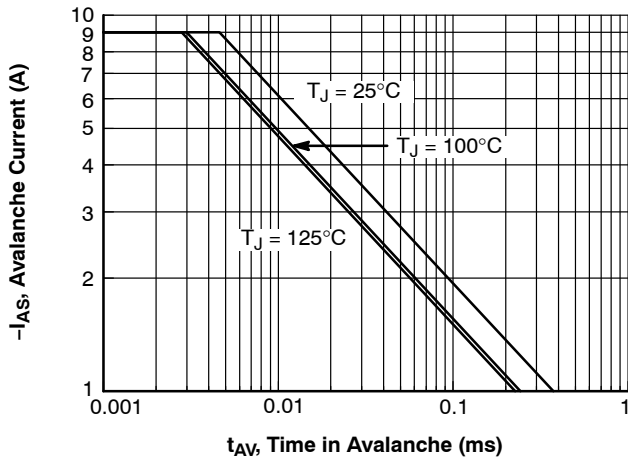


Figure 9. Unclamped Inductive Switching Capability

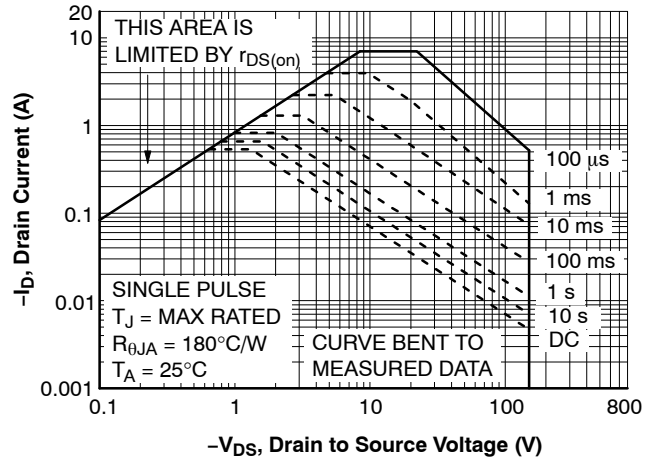


Figure 10. Forward Bias Safe Operating Area

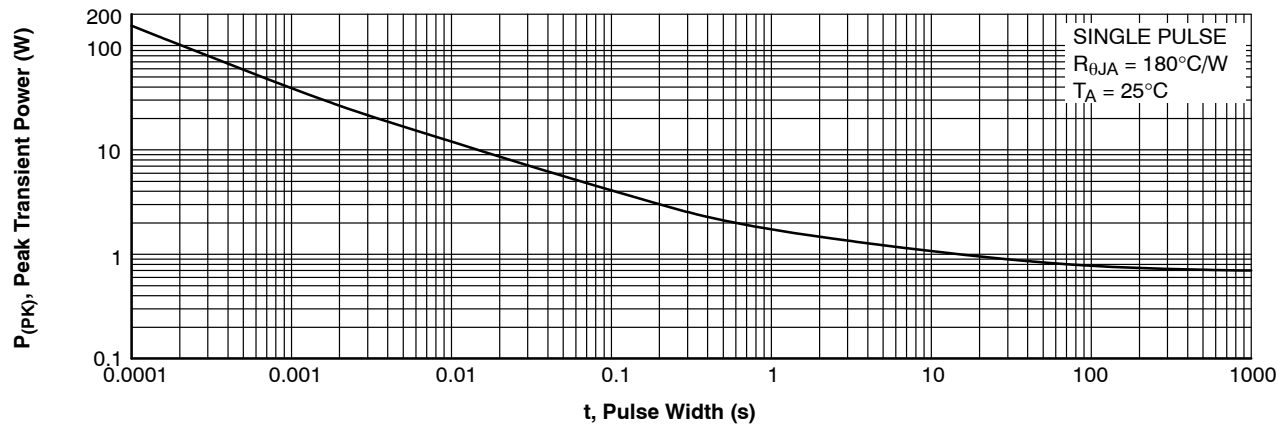


Figure 11. Single Pulse Maximum Power Dissipation

FDN86265P

TYPICAL CHARACTERISTICS (CONTINUED)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

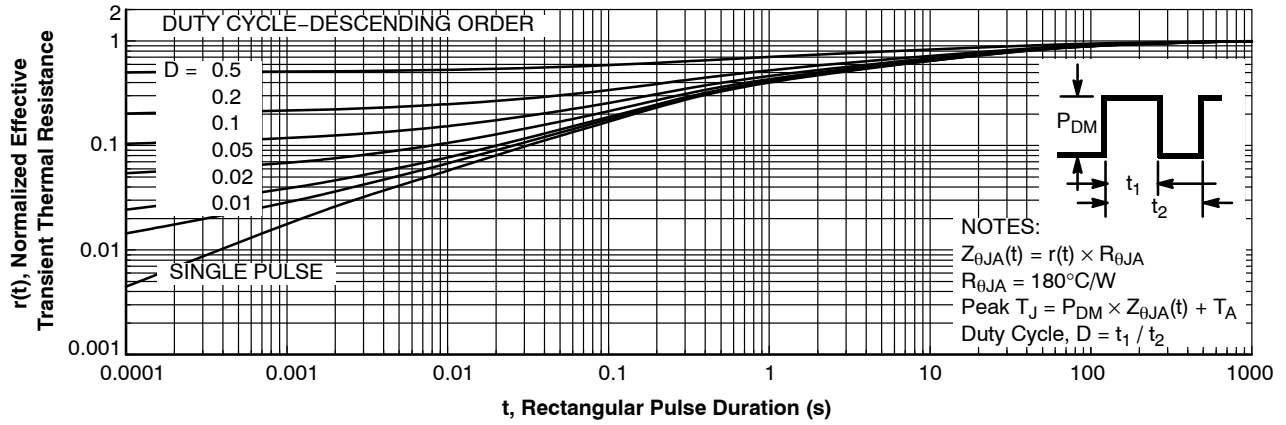
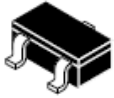


Figure 12. Junction-to-Ambient Transient Thermal Response Curve

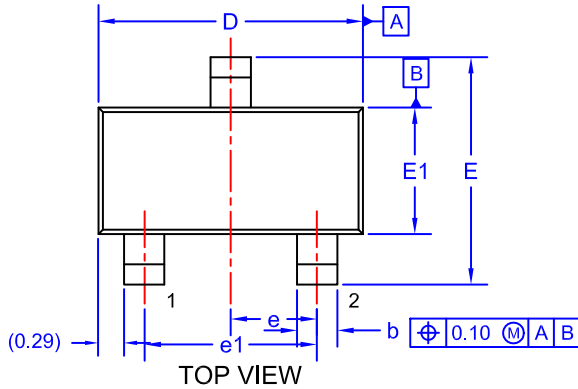
POWERTRENCH is a registered trademark of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries.

SUPERSOT is a trademark of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries.



SOT-23/SUPERSOT™ -23, 3 LEAD, 1.4x2.9
CASE 527AG
ISSUE A

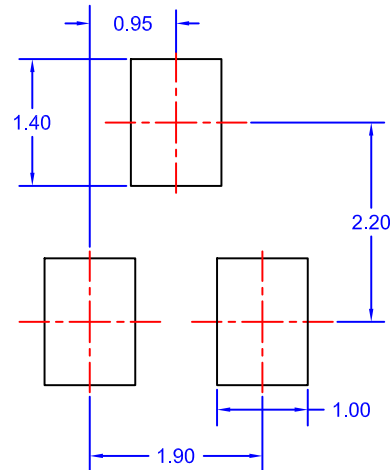
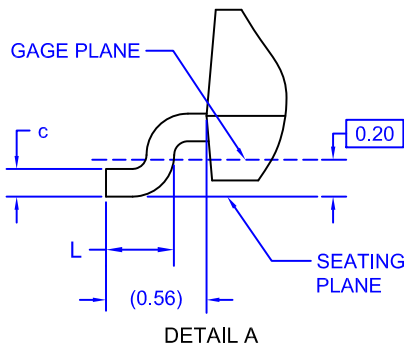
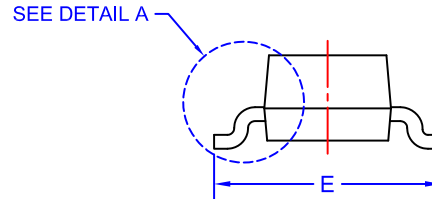
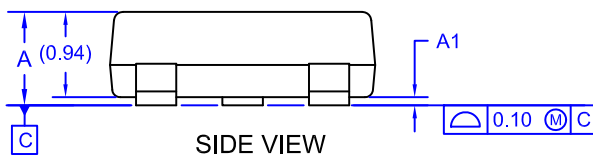
DATE 09 DEC 2019



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

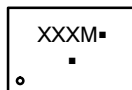
DIM	MIN.	NOM.	MAX.
A	0.85	0.95	1.12
A1	0.00	0.05	0.10
b	0.370	0.435	0.508
c	0.085	0.150	0.180
D	2.80	2.92	3.04
E	2.31	2.51	2.71
E1	1.20	1.40	1.52
e	0.95 BSC		
e1	1.90 BSC		
L	0.33	0.38	0.43



LAND PATTERN RECOMMENDATION*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Month Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON34319E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOT-23/SUPERSOT-23, 3 LEAD, 1.4X2.9	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales